Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

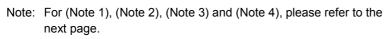
TPC8001

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

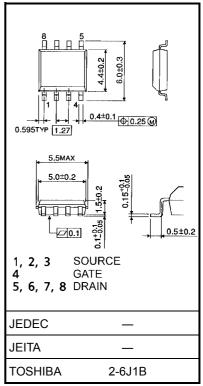
- Small footprint due to small and thin package
- Low drain-source ON resistance $: R_{DS} (ON) = 15 m\Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 11 \text{ S} (\text{typ.})$
- Low leakage current $: I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$ •
- Enhancement-mode $: V_{th} = 0.8 \sim 2.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ ID} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Character	ristics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	30	V	
Drain-gate voltage (R	t _{GS} = 20 kΩ)	V _{DGR}	30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	ID	7	А	
Diameditent	Pulse (Note 1)	I _{DP}	28		
Drain power dissipati	on (t = 10 s) (Note 2a)	PD	2.4	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	PD	1.0	W	
Single pulse avalanch	ne energy (Note 3)	E _{AS}	64	mJ	
Avalanche current		I _{AR}	7	А	
Repetitive avalanche	energy Note 2a) (Note 4)	E _{AR}	0.24	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature	range	T _{stg}	−55 to 150	°C	

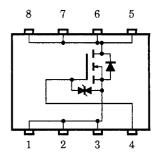


This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

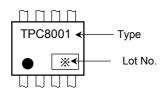
Circuit Configuration



Thermal Characteristics

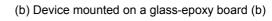
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	52.1	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

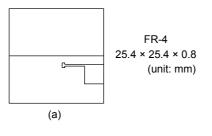
Marking (Note 5)

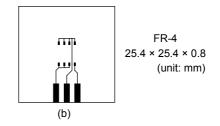


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)





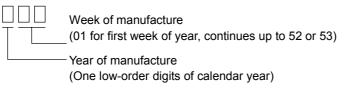


Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 7 A

Note 4: Reptitve rating; pulse width limited by maximum channel temperature

Note 5: \bullet on lower left of the marking indicates Pin 1.

* Weekly code: (Three digits)

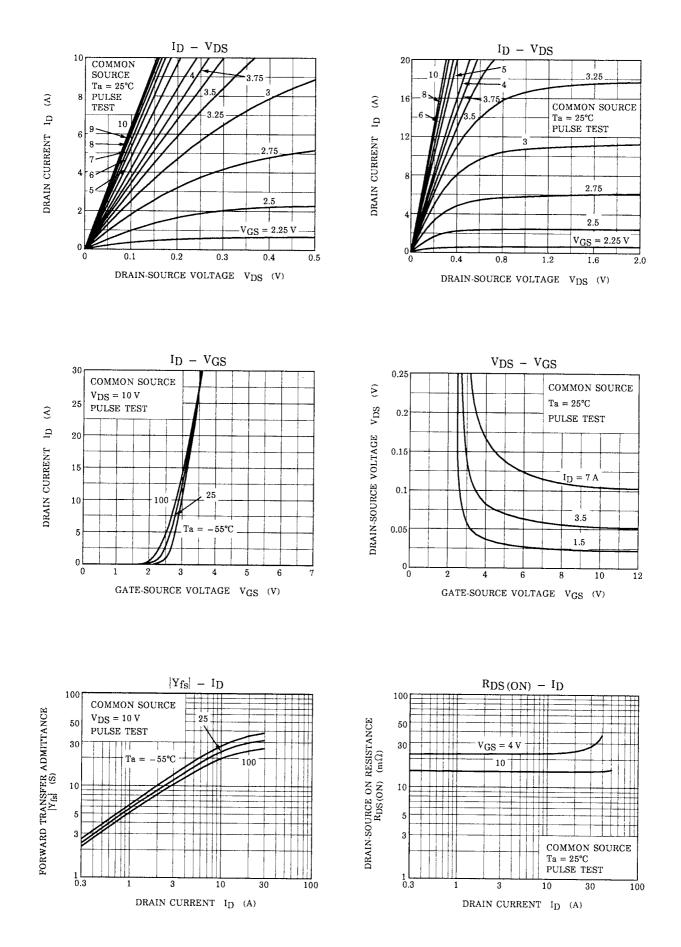


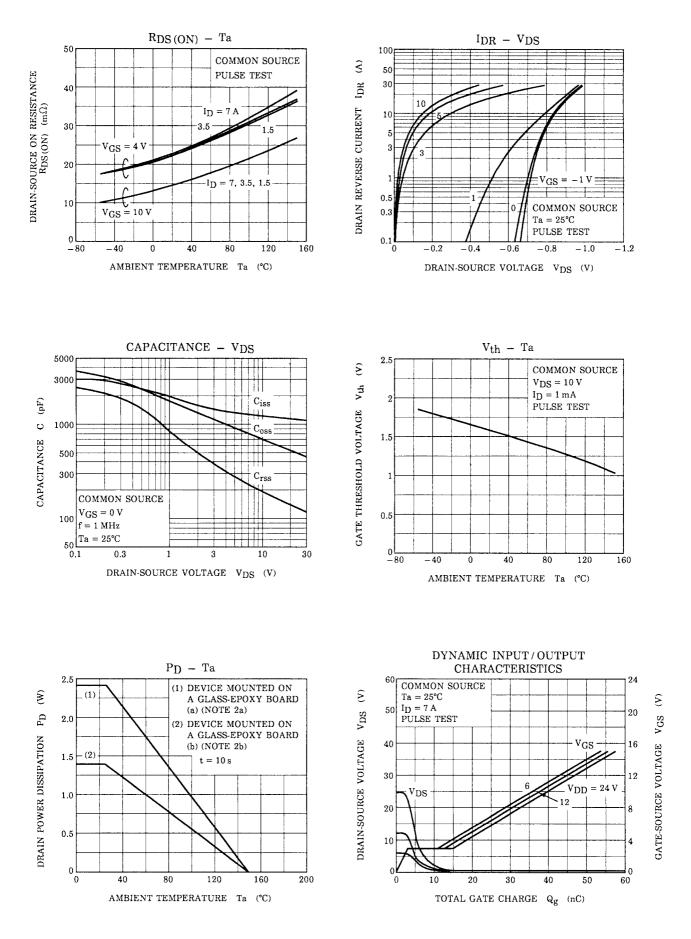
Electrical Characteristics (Ta = 25°C)

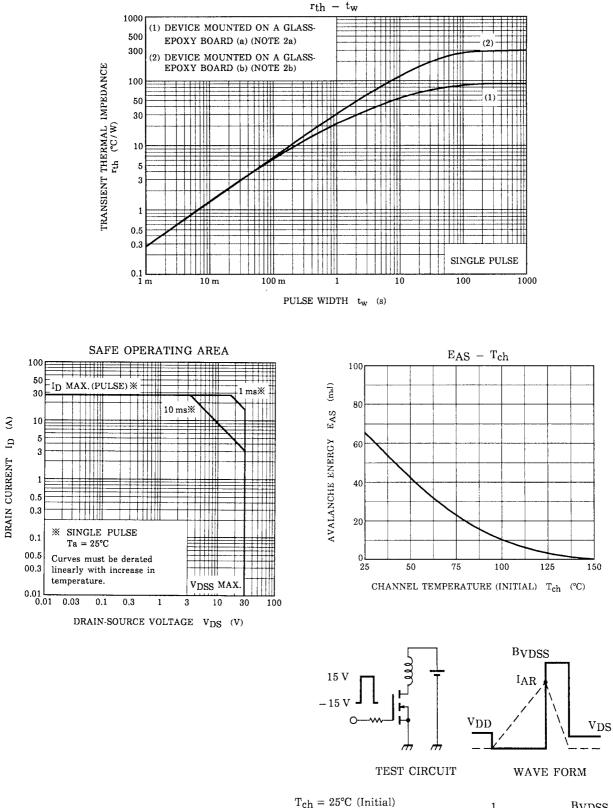
Charae	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	—	±10	μA
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V		_	10	μA
Drain-source bi	rain-source breakdown voltage		I _D = 10 mA, V _{GS} = 0 V	30	_	_	V
Gate threshold	voltage	vakdown voltage V (BR) DSS ID = 10 mA, VGS = 0 V 30 $-$ oltage V _{th} VDS = 10 V, ID = 1 mA 0.8 $-$		_	2.0	V	
	Nragiotopoo	R _{DS (ON)}	V _{GS} = 4 V, I _D = 3.5 A		25	30	mΩ
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 10 V, I _D = 3.5 A		16	20	mΩ
Forward transfer admittance		Y _{fs}	V _{DS} = 10 V, I _D = 3.5 A	5.5	11	_	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		1250	_	pF
Reverse transfer capacitance		C _{rss}			190	_	
Output capacitance		Coss			760	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 \text{ V}}{}_{0 \text{ V}} \stackrel{I_{D} = 3.5 \text{ A}}{}_{VOUT} \\ \stackrel{\circ}{}_{W} }{}_{W} }{} }{}_{W} }{} }}{} }{} }{} }{} }{$	_	9	_	- ns
	Turn-on time	t _{on}		_	17	_	
	Fall time	t _f		_	24	_	
	Turn-off time	t _{off}		_	100	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	40	_	nC
Gate-source charge		Q _{gs}	V _{DD} ≈ 24 V, V _{GS} = 10 V, I _D = 7 A		27	_	
Gate-drain ("miller") charge		Q _{gd}]		13	_	

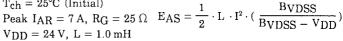
Source–Drain Ratings and Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	—	_	_	28	А
Forward voltage	(diode)	V _{DSF}	I _{DR} = 7 A, V _{GS} = 0 V	— — — -1.2		V	









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